Fairchild Semiconductor Product Package Material Disclosure

Package Type	PQFN-8 3.3X3.3 (Power 33)						
Weight of Package (grams)	3.21E-02						
Component	Material	Wt in grams	Substance or Material	Wt% in component	Wt% in Finished Product	CAS #	Parts per Million
Lead Frame	Metal Alloy	1.25E-02			38.99		389854
			Copper	97.43	37.98	7440-50-8	379834
			Iron	2.40	0.94	7439-89-6	9356
			Zinc	0.13	0.05	7440-66-6	507
Encapsulation	Epoxy	1.66E-02			51.60		515998
			Silica	92.00	47.47		474718
			Epoxy Resin	5.00	2.58		25800
			Phenol Resin	3.00	1.55		15480
Plating	Solder	1.60E-05			0.05		498
			Nickel	90.00	0.04	7440-02-0	448
			Palladium	9.00	0.00	7440-05-3	45
			Gold	1.00	0.00	7440-57-5	5
Chip	Silicon	2.01E-03			6.26		62621
			Silicon and trace metals	99.99	6.26	7440-21-3	62614
Die Attach	Adhesive	5.83E-04			1.81		18145
			Silver	80.00	1.45	7440-22-4	14516
			Resin	20.00	0.36		3629
Wire Bond	Aluminum Wire	4.14E-04			1.29		12885
			Aluminum	99.99	1.29	7429-90-5	12884
			Nickel	0.01	0.00	7440-02-0	1

Materials Disclosure Disclaimer

The information provided in this Materials Disclosure is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company. Also, there may not be information included in this statement regarding the minute amounts of dopant and metal materials contained within the electrically active or passive devices contained within the finished product.